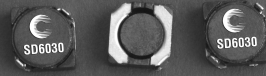


# Low-Profile Power Inductors

## SD6030 Series



### SMD Device



### Description

- 125°C maximum total temperature operation
- Low profile surface mount inductors
- 6.0 x 6.0 x 3.0mm maximum surface mount package
- Ferrite core material
- Shielded drum core reduces EMI
- Inductance range from 2.7µH to 660µH
- Current range from 0.16 to 4.08 Amps
- Frequency range up to 1MHz

### Applications

- Notebook computers, digital cameras
- High Power LED driver
- Battery power, TFT-LCD Bias supplies
- Gaming consoles, GPS receivers
- Wireless notebook adapters
- Wireless handsets, handheld instruments

### Environmental Data

- Storage temperature range: -40°C to +125°C
- Operating temperature range: -40°C to +125°C (ambient plus self-temperature rise)
- Solder reflow temperature: J-STD-020D compliant

### Packaging

- Supplied in tape and reel packaging, 2000 per 13" diameter reel

### Product Specifications

Part Number <sup>5</sup>	OCL <sup>1</sup> µH ± 30%	I <sub>rms</sub> <sup>2</sup> (Amps)	I <sub>sat</sub> <sup>3</sup> (Amps)	Typ. DCR mΩ @ 20°C	Max DCR mΩ @ 20°C	K-factor <sup>4</sup>
SD6030-2R7-R	2.7	4.08	2.60	13	18	34
SD6030-3R3-R	3.3	3.54	2.40	18	24	30
SD6030-4R2-R	4.1	3.11	2.20	23	31	27
SD6030-5R0-R	4.9	2.81	1.90	28	38	24
SD6030-5R8-R	5.8	2.58	1.80	33	45	22
SD6030-7R8-R	7.8	2.38	1.60	39	53	19
SD6030-100-R	9.3	2.15	1.30	48	65	17
SD6030-120-R	11.3	1.99	1.20	56	76	16
SD6030-150-R	14.1	1.71	1.10	76	103	14
SD6030-180-R	17.1	1.65	1.00	82	110	13
SD6030-220-R	20.4	1.57	0.90	90	122	12
SD6030-270-R	26.0	1.31	0.85	130	175	11
SD6030-330-R	32.4	1.26	0.75	140	189	9.3
SD6030-360-R	34.4	1.19	0.70	157	212	8.7
SD6030-440-R	44.0	1.10	0.62	185	250	7.9
SD6030-520-R	52.0	0.99	0.58	226	305	7.2
SD6030-680-R	65.6	0.92	0.52	263	355	6.5
SD6030-820-R	81.6	0.80	0.46	343	463	5.9
SD6030-101-R	94.4	0.76	0.42	385	520	5.6
SD6030-121-R	110.1	0.70	0.40	517	620	5.6
SD6030-151-R	144.5	0.64	0.35	608	730	5.0
SD6030-181-R	175.7	0.55	0.32	817	980	4.5
SD6030-221-R	210.9	0.50	0.30	1000	1200	4.0
SD6030-271-R	264.2	0.44	0.27	1300	1560	3.6
SD6030-331-R	313.5	0.38	0.25	1733	2080	3.3
SD6030-391-R	373.7	0.35	0.22	2083	2500	3.0
SD6030-471-R	460.0	0.33	0.20	2250	2700	2.8
SD6030-561-R	546.2	0.30	0.18	2767	3320	2.5
SD6030-681-R	659.4	0.27	0.16	3458	4150	2.3

1) Open Circuit Inductance Test Parameters: 100kHz, 0.1V, 0.0Adc.

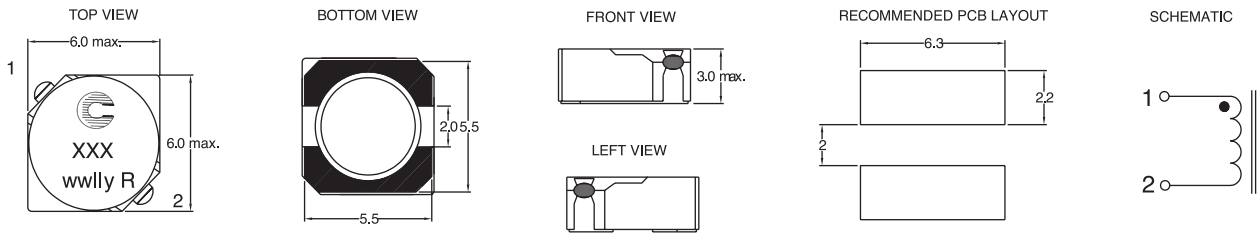
2) I<sub>rms</sub>: DC current for an approximate ΔT of 40°C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125°C under worst case operating conditions verified in the end application.

3) I<sub>sat</sub>: Amps peak for 35% rolloff (@25°C)

4) K-factor: Used to determine B<sub>p-p</sub> for core loss (see graph). B<sub>p-p</sub> = K\*L\*ΔI, B<sub>p-p</sub> (mT), K: (K factor from table), L: (Inductance in µH), ΔI (Peak to peak ripple current in Amps).

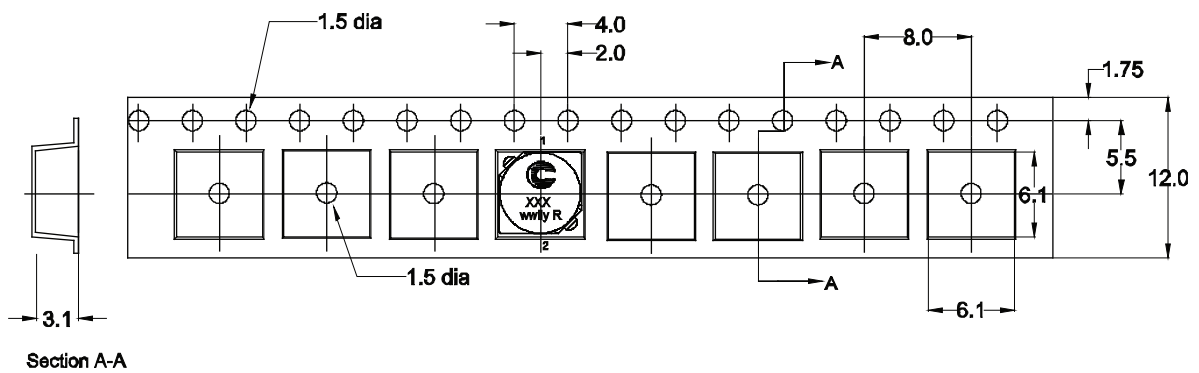
5) Part Number Definition: SD6030-xxx-R  
 SD6030 = Product code and size; -xxx = inductance value in µH;  
 R = decimal point; If no R is present, third character = # of zeros.  
 -R suffix = RoHS compliant

### Dimensions - mm



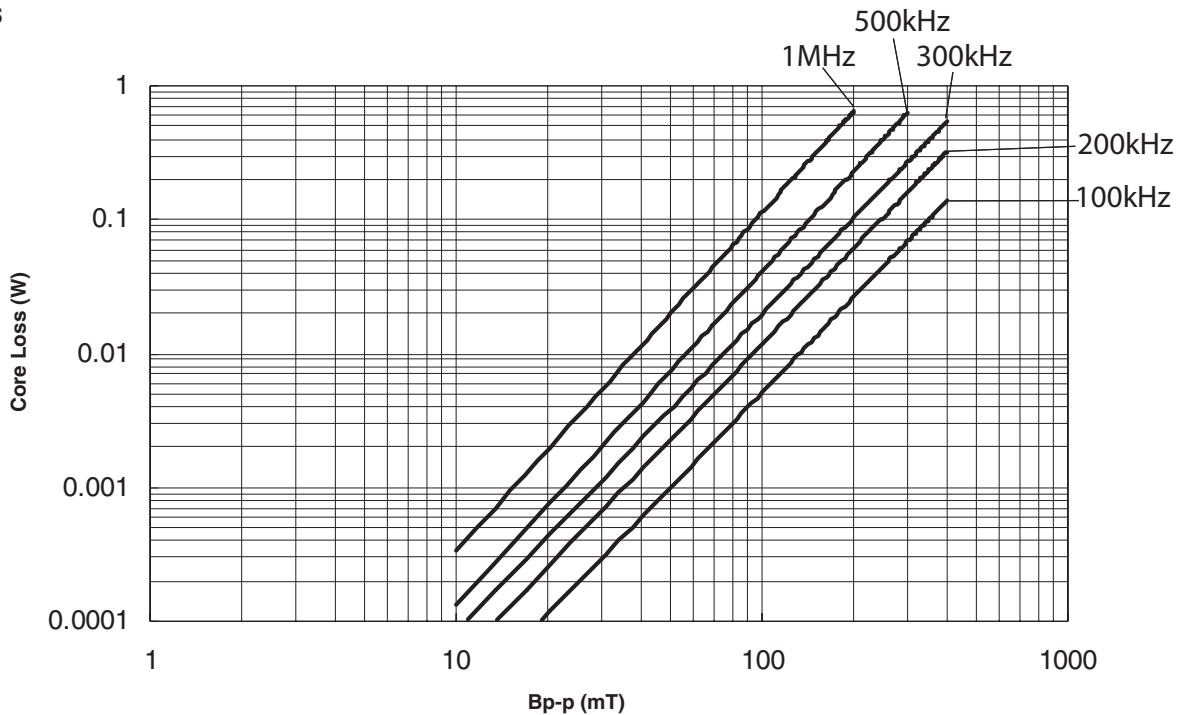
Part Marking: Coiltronics logo, xxx = Inductance value in uH. R = decimal point. If no R is present third character = # of zeros, wwlly or wwllly = Date code, R = Revision level.

### Packaging Information - mm

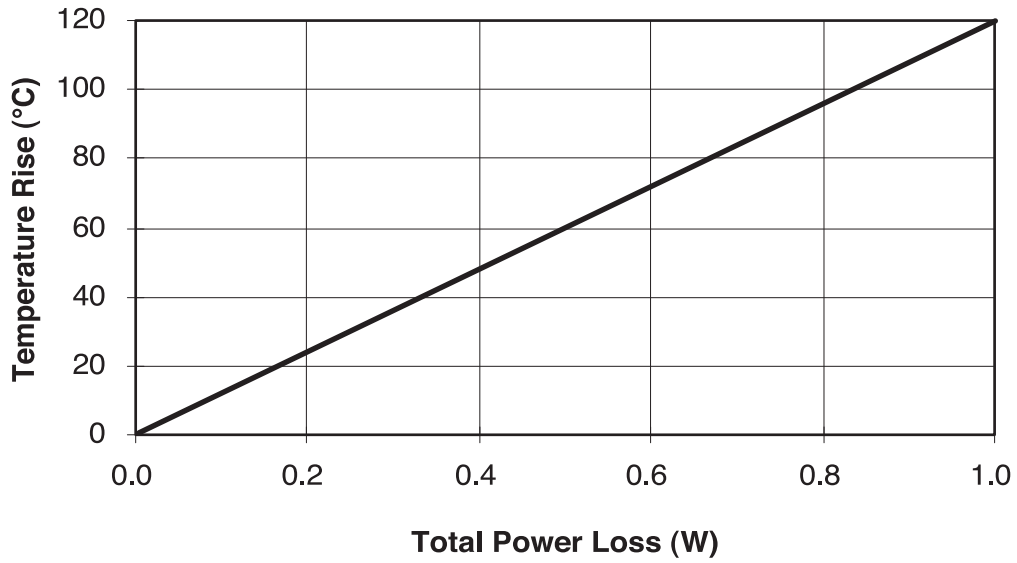


Parts packaged on 13" diameter reel, 2000 parts per reel.

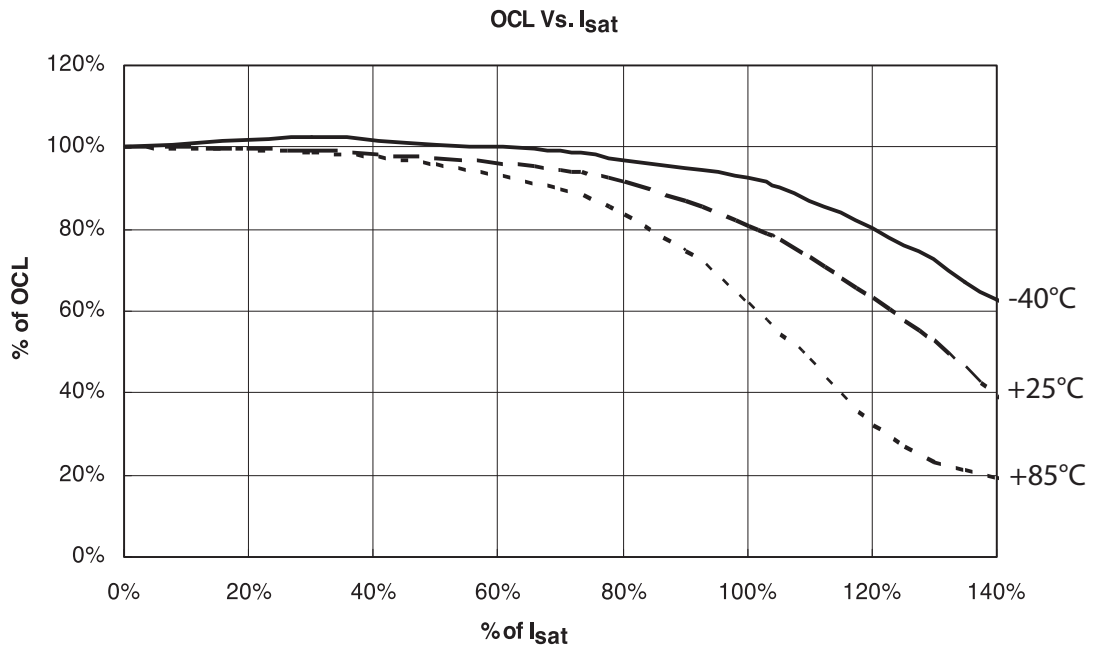
### Core Loss



### Temperature Rise vs. Loss



### Inductance Characteristics



## Solder Reflow Profile

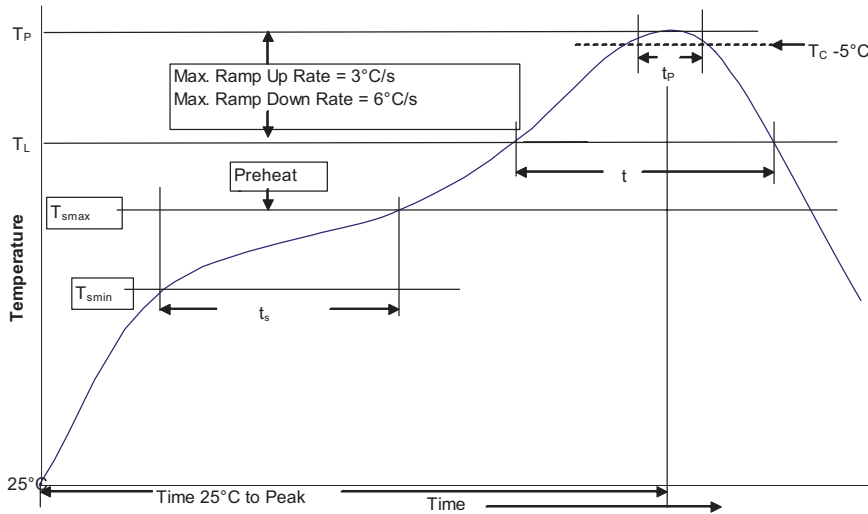


Table 1 - Standard SnPb Solder (T<sub>c</sub>)

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> ≥350
<2.5mm	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T<sub>c</sub>)

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350 - 2000	Volume mm <sup>3</sup> >2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

## Reference JDEC J-STD-020D

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak	• Temperature min. (T <sub>smin</sub> )	100°C
	• Temperature max. (T <sub>smax</sub> )	150°C
	• Time (T <sub>smin</sub> to T <sub>smax</sub> ) (t <sub>s</sub> )	60-120 Seconds
Average ramp up rate T <sub>smax</sub> to T <sub>p</sub>	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T <sub>L</sub> )	183°C	217°C
Time at liquidous (t <sub>L</sub> )	60-150 Seconds	60-150 Seconds
Peak package body temperature (T <sub>p</sub> )*	Table 1	Table 2
Time (t <sub>p</sub> )** within 5 °C of the specified classification temperature (T <sub>c</sub> )	20 Seconds**	30 Seconds**
Average ramp-down rate (T <sub>p</sub> to T <sub>smax</sub> )	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

\* Tolerance for peak profile temperature (T<sub>p</sub>) is defined as a supplier minimum and a user maximum.

\*\* Tolerance for time at peak profile temperature (t<sub>p</sub>) is defined as a supplier minimum and a user maximum.

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